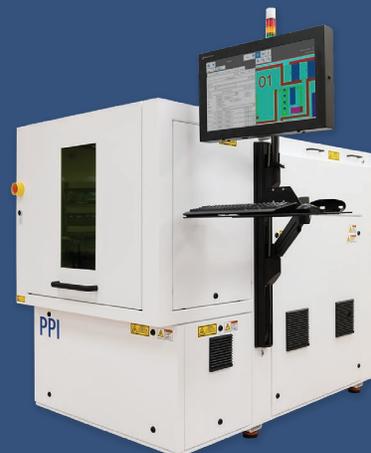


# RapiTrim™-R-IR

Chip-Resistor Trimming System  
with 1.06 μm Laser

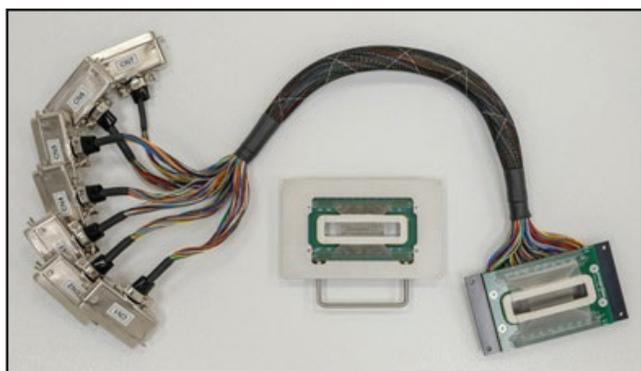


## The RapiTrim Chip-R Solutions

RapiTrim-R systems are ideally suited to volume production trim and test using industry-standard probe cards, optimized for chip resistor substrates up to 60 x 70 mm.

The cable-free RapiTrim probe card mechanism is the latest in technology advances from PPI, providing greater operational convenience and more rapid probe card exchange than what is available on traditional systems.

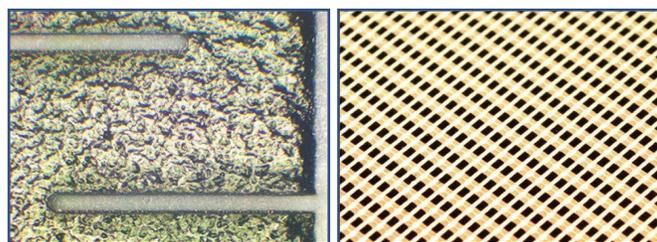
- High performance 4-axis prober with precision step-and-repeat substrate handler.
- Fast probe card exchange and automated realignment routine.
- Profiled motion trajectory control improves probe tip placement and contact precision.
- Scan field up to 60mm wide to cover complete row of resistors without repositioning.
- Programming is not required for normal job setup. Scripting is available directly within the job editor for custom sequencing.



Traditional and new cable-free probe card.

## RapiTrim-R with IR (1.06 μm) Laser

Long-life, low-maintenance air-cooled fibre laser producing high peak power pulses for rapid ablation of resistor material while minimizing damage to the substrate. Suitable for both thick and thin film materials. Configurable for a range of spot sizes.



Serpentine legs in thick film on alumina (L) and an array of chip resistors (R).

## Key RapiTrim Benefits

- Full process control for optimization of approach-to-target.
- Process accuracy from advanced beam positioning and laser pulse control.
- Real-time measurement system prevents trim overshoot.
- Process integrity provided by high accuracy measurement system and auto-calibration functions.
- Fast, automated job setup through extensive support of DXF import.
- Efficient operation and job setup through clear, intuitive touchscreen user interface.

RapiTrim - The Future of Resistor Trimming™

# ProSys™ Software - Your Key to Process Control and Efficiency

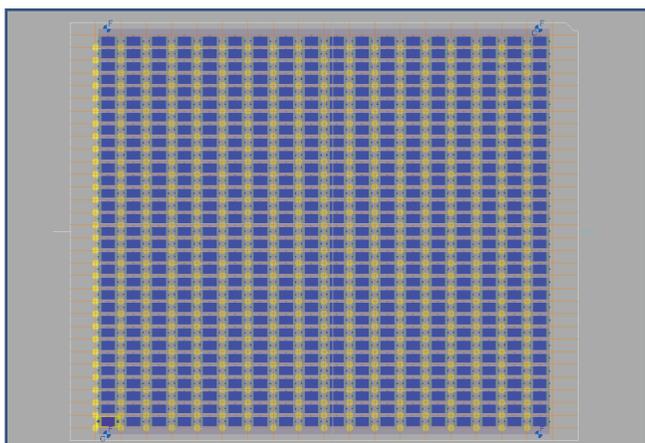
## User Interface

The ProSys user interface is a modern solution to allow customers the control they want without the need to be software programmers. The resulting efficiency in job creation and operation turns into improved profitability.

Simple. All control and status screens are laid out for optimum visibility.

Intuitive. With the touchscreen panel, interaction is more like a mobile device and less like a computer.

Powerful. The simplicity masks the power available to create jobs quickly, optimize processing, rapidly change jobs, monitor results, receive maintenance prompts, and seamlessly interact with external devices.



Screen capture showing resistor layout.

## Job Creation

Set up jobs directly from CAD. Extensive DXF file import support automates and speeds job creation.

Manual job creation, or editing of an existing job, is done through an interactive graphical map of components, circuit features, alignment targets and trims.

Trim and measurement tools can be shared by resistors of different sizes and orientations, minimizing setup steps.

Use the standard trim tools or create your own with the custom cut editor.

Interactive graphical process library editor; no programming required. Process sequence customization is available when needed through scripting support directly in the job editor.

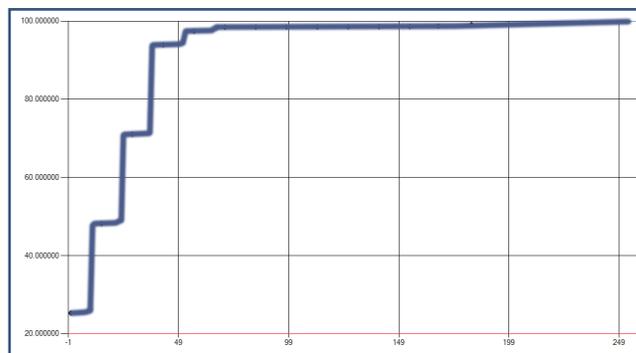
Optional active circuit trimming using standard internal or external instruments.

## Process Control and Optimization

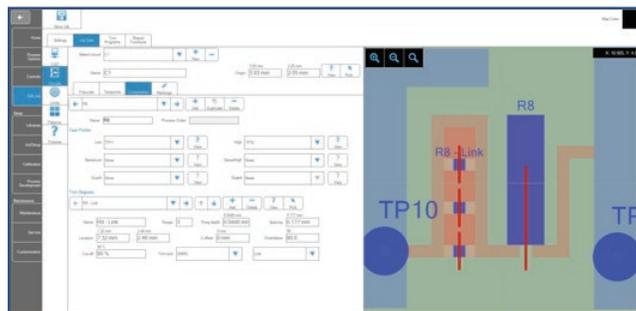
The resistance change of each laser pulse is monitored using PPI's proprietary, real-time measurement system. This allows the resistance data to be output as the Trim Profile, invaluable during process development.

In addition, any trim cut can be segmented, with different laser parameters applied to each segment.

The combination of pulse-by-pulse measurement and cut-to-cut control allows process engineers unprecedented management of the approach to target, optimizing both speed and accuracy.



Trim profile of ladder cuts followed by a plunge to target.



Screen capture showing ladder and plunge trim setup.

## External Instrument Support

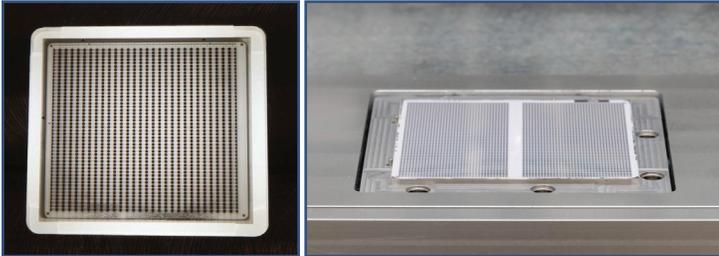
The trim controller can interface to external instrumentation for passive and active trim operations using standard LAN (LXI) or GPIB interfaces. Such instrumentation can be digital multimeters, source-measure units, signal generators, power supplies or external loads.

The control of and reporting from these external instruments is integrated within the ProSys user interface. Space is provided within the RapiTrim enclosure for a standard 19-inch rack to mount such equipment.

## Part Loading and Fixturing

### Advanced Fixturing

Vacuum hold-down is used on chuck tops. Custom fixture plates and advanced functions such as temperature control and backlighting can also be provided.



*Backlit substrate (L) and temperature-controlled chuck (R).*

### Automation Options

- Stack loader, internal to the RapiTrim enclosure
- Magazine load / unload compatibility with SMEMA standard interfaces / turnkey solutions.

Both capable of unattended high volume operation.



*Automation option.*



## Probing and Measurement

### Probe Cards

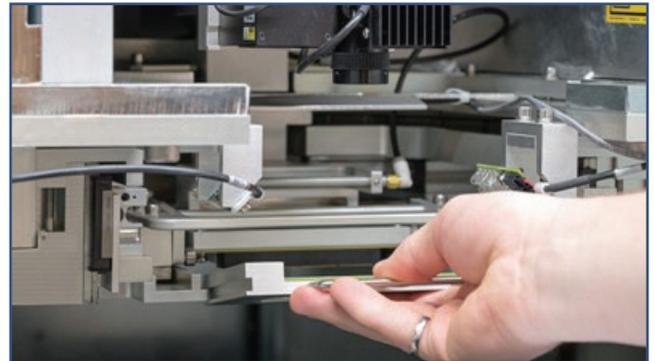
The probe needles for the DUT are sequentially connected to four independent source-measure units, each capable of providing Force, Sense and Guard signals.

Accepts the new cable-free chip-R probe cards for improved performance and ease of use.

Fast, accurate, and automatic planarization of probe cards.

Quick-release clamp allow easy exchange of probe cards within seconds; no need to plug in multiple connectors.

Motion trajectory control improves tip placement accuracy and contact precision.



*Easy exchange of cable-free chip-R probe cards.*

### Switch Matrix

The standard switch matrix provides the following functionality:

- Mapping of the four source-measure unit channels to four independent matrix card channels
- Switching of external instrument signals into the matrix card channels
- Two independent banks of precision low-TCR decade resistors for bridge-like nulling applications
- Switchable ground reference nodes
- A 1A precision current source for low Ohm applications, controlled by the source-measure units

## RapiTrim Specifications<sup>1</sup>

### Trim Types and Accuracy

- Single-plunge, double-plunge, L, L-Vernier, scan, serpentine and custom multi-leg cut types
- Advanced laser pulse control optimizes cut quality and trim tolerances per cut.

### Optical System

- High reliability fiber laser. Air cooled, long lifetime with IR wavelength
- Spot size: 10 - 60 μm
- Automated laser power calibration with integrated power meter
- Automated vision system for precision alignment (with offset and rotation compensation)
- Low mag camera field: 20 mm (diag)
- High mag camera field: <3 mm (diag)
- Colinear and low-angle illumination
- Beam scanning field: up to 60 mm (spot size dependent)
- Beam placement accuracy 10 μm (3 sigma) over substrate area
- Beam position resolution <0.5 μm
- Telecentric scan optics on precision z-axis focus stage with 0.5 μm resolution

### Mechanical System

- Precision linear motor XY stages with linear optical encoder feedback
- Process area: 300 mm x 300 mm
- XY Travel: 300 mm x 450 mm
- XY Accuracy: <5 μm
- XY Resolution: 0.1 μm
- XY Repeatability: 1 μm

### Probing

- Cable-free probe cards in chip-R format
- Z travel: 15 mm
- Z resolution: 0.5 μm
- Servo controlled Z velocity and acceleration
- Roll and pitch adjustment: ± 1°
- Roll and pitch resolution: <5 μRad
- Rotation: ± 5°
- Rotation resolution: <5 μRad
- Automated roll, pitch, Z and rotation calibration

### Measurement System

- Fully programmable force voltage or force current
- Switching matrix up to 512 ch
- Resistor range: 0.1 Ω to 1 GΩ
- Ratio trim and guard functions
- Resistance measurement accuracy:

Low Range (<10 Ω) ±0.05% (±0.05% / R)\*

Mid- Range: (10 Ω to 1 MΩ) ± 0.02%\*

High Range (>1 MΩ): ± 0.02% ± 0.02% per MΩ\*

- Voltage Source Ranges and Measurement Accuracy:

Range	Resolution	Accuracy (% FSR)*
±20V	80 μV	± 0.01%
±2V	8 μV	± 0.01%

- Current Source Ranges and Measurement Accuracy

Range	Resolution	Accuracy (% FSR)*
4uA	30 pA	± 0.1%
40uA	300 pA	± 0.05%
400uA	3 nA	± 0.01%
4mA	30 nA	± 0.01%
25mA	200 nA	± 0.01%
250mA	2 μA	± 0.05%

\*after standard calibration, full Kelvin.

FSR = full scale range.

### Part Handling

- Interface to stack loaders or SMEMA-compatible conveyor.

### Software

- Auto-import and job creation from DXF
- Full process control for optimization of approach-to-target
- Configurable part marking and serialization
- Automatic system run-time calibration
- All measurement data logged as part of normal operation
- Real-time system diagnostics and health logging
- Internet connection allows factory personnel to provide remote support

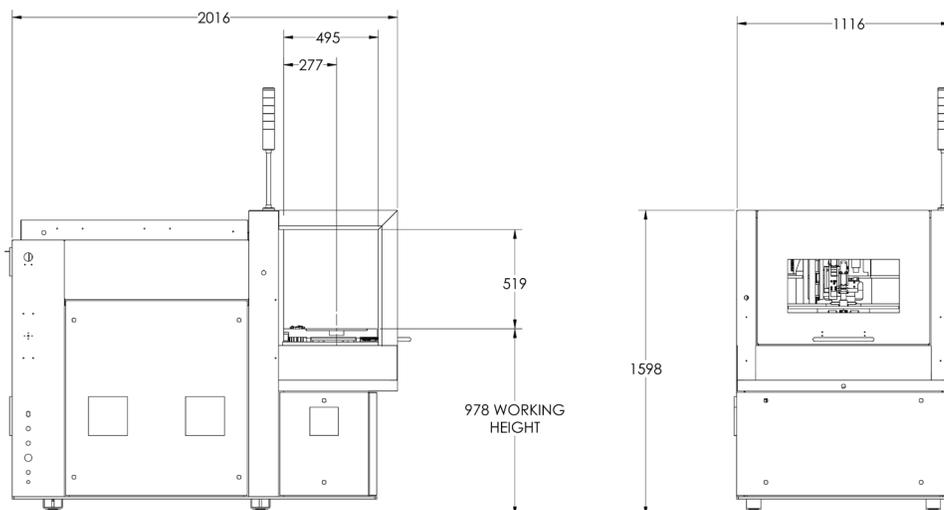
### Options

- Automatic part loader/unloader
- Optional network interface customization
- Automated barcode reading functions and job creation/loading
- Custom fixturing
- External instrument support

### Facilities Requirements

- Electrical: 200-240 VAC, 1ph, 30A, 50/60Hz
- Exhaust: ablation debris removal through 38 mm diameter duct.
- Compressed air: 6 bar, 56 l/min, dry and oil free

<sup>1</sup> Specifications are subject to revision



Turnkey Systems

Industry 4.0, IIoT

DXF Auto Import

SMEMA Compatible